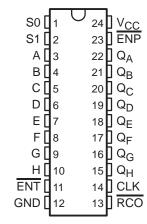
- Fully Programmable With Synchronous Counting and Loading
- SN74ALS867A and 'AS867 Have Asynchronous Clear; SN74ALS869 and 'AS869 Have Synchronous Clear
- Fully Independent Clock Circuit Simplifies Use
- Ripple-Carry Output for n-Bit Cascading
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (NT) and Ceramic (JT) 300-mil DIPs

#### description

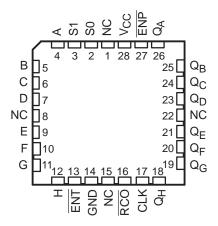
These synchronous, presettable, 8-bit up/down counters feature internal-carry look-ahead circuitry for cascading in high-speed counting applications. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincidentally with each other when so instructed by the count-enable (ENP, ENT) inputs and internal gating. This mode of operation eliminates the output counting spikes normally associated with asynchronous (ripple-clock) counters. A buffered clock (CLK) input triggers the eight flip-flops on the rising (positive-going) edge of the clock waveform.

These counters are fully programmable; they may be preset to any number between 0 and 255. The load-input circuitry allows parallel loading of the cascaded counters. Because loading is synchronous, selecting the load mode disables the counter and causes the outputs to agree with the data inputs after the next clock pulse.

SN54AS867, SN54AS869 . . . JT PACKAGE SN74ALS867A, SN74ALS869, SN74AS867, SN74AS869 . . . DW OR NT PACKAGE (TOP VIEW)



SN54AS867, SN54AS869 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

The carry look-ahead circuitry provides for cascading counters for n-bit synchronous applications without additional gating. Two count-enable ( $\overline{\text{ENP}}$  and  $\overline{\text{ENT}}$ ) inputs and a ripple-carry ( $\overline{\text{RCO}}$ ) output are instrumental in accomplishing this function. Both  $\overline{\text{ENP}}$  and  $\overline{\text{ENT}}$  must be low to count. The direction of the count is determined by the levels of the select (S0, S1) inputs as shown in the function table.  $\overline{\text{ENT}}$  is fed forward to enable  $\overline{\text{RCO}}$ .  $\overline{\text{RCO}}$  thus enabled produces a low-level pulse while the count is zero (all outputs low) counting down or 255 counting up (all outputs high). This low-level overflow-carry pulse can be used to enable successive cascaded stages. Transitions at  $\overline{\text{ENP}}$  and  $\overline{\text{ENT}}$  are allowed regardless of the level of CLK. All inputs are diode clamped to minimize transmission-line effects, thereby simplifying system design.

These counters feature a fully independent clock circuit. With the exception of the asynchronous clear on the SN74ALS867A and 'AS867, changes at S0 and S1 that modify the operating mode have no effect on the Q outputs until clocking occurs. For the 'AS867 and 'AS869, any time  $\overline{\text{ENP}}$  and/or  $\overline{\text{ENT}}$  is taken high,  $\overline{\text{RCO}}$  either goes or remains high. For the SN74ALS867A and SN74ALS869, any time  $\overline{\text{ENT}}$  is taken high,  $\overline{\text{RCO}}$  either goes or remains high. The function of the counter (whether enabled, disabled, loading, or counting) is dictated solely by the conditions meeting the stable setup and hold times.



SDAS115C - DECEMBER 1982 - REVISED JANUARY 1995

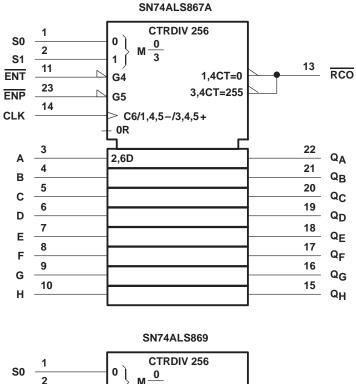
#### description (continued)

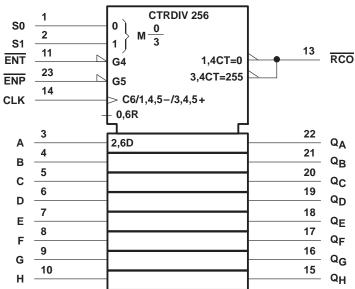
The SN54AS867 and SN54AS869 are characterized for operation over the full military temperature range of  $-55^{\circ}$ C to 125°C. The SN74ALS867A, SN74ALS869, SN74AS867, and SN74AS869 are characterized for operation from 0°C to 70°C.

#### **FUNCTION TABLE**

S1	S0	FUNCTION
L	L	Clear
L	Н	Count down
Н	L	Load
Н	Н	Count up

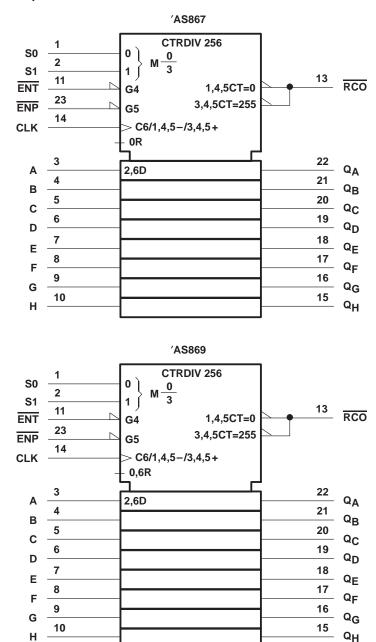
# logic symbols†





<sup>&</sup>lt;sup>†</sup> These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DW, JT, and NT packages.

#### logic symbols (continued)†

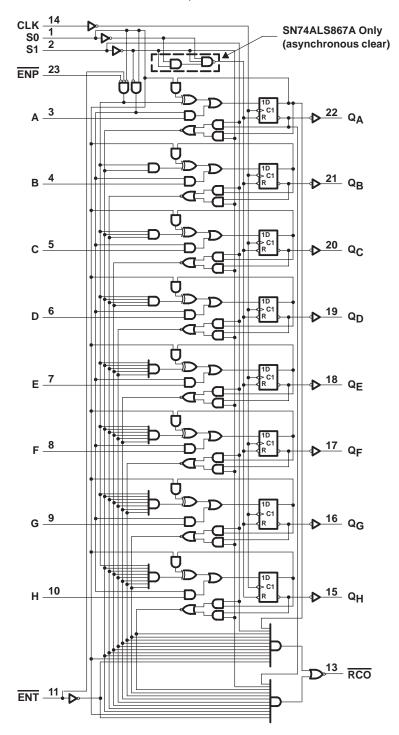


<sup>†</sup> These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DW, JT, and NT packages.



#### logic diagram (positive logic)

#### SN74ALS867A, SN74ALS869



Pin numbers shown are for the DW, JT, and NT packages.



#### logic diagram (positive logic)

SDAS115C - DECEMBER 1982 - REVISED JANUARY 1995

# 'AS867, 'AS869 'AS867 Only (asynchronous clear) ENT 11 13 RCO ENP 23 CLK 14 22 Q<sub>A</sub> A -3 20 QC 19 Q<sub>D</sub> D 17 Q<sub>F</sub> 16 Q<sub>G</sub> H \_\_\_\_\_\_\_\_\_\_\_

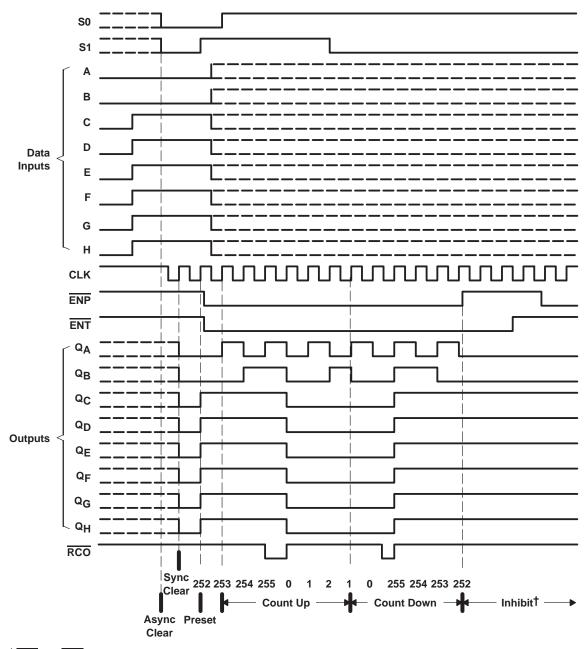
Pin numbers shown are for the DW, JT, and NT packages.



#### typical clear, preset, count, and inhibit sequences

The following sequence is illustrated below:

- 1. Clear outputs to zero (SN74ALS867A and 'AS867 are asynchronous; SN74ALS869 and 'AS869 are synchronous.)
- 2. Preset to binary 252
- 3. Count up to 253, 254, 255, 0, 1, and 2
- 4. Count down to 1, 0, 255, 254, 253, and 252
- 5. Inhibit



† ENT and ENP both must be low for counting to occur.



SDAS115C - DECEMBER 1982 - REVISED JANUARY 1995

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

#### recommended operating conditions

			SN7	'4ALS86	7A	UNIT
			MIN	NOM	MAX	UNII
Vcc	Supply voltage		4.5	5	5.5	V
VIH	High-level input voltage		2			V
V <sub>IL</sub>	Low-level input voltage				0.8	V
loн	High-level output current				-0.4	mA
loL	Low-level output current				8	mA
fclock	Clock frequency		0		35	MHz
tw(clock)	Pulse duration, CLK high or low		14			ns
tw(clear)	Pulse duration of clear pulse, S0 and S1 low		10			ns
		Data inputs A-H	10			
		ENP or ENT	15			
t <sub>su</sub>	Setup time before CLK↑	S0 low and S1 high (load)	12			ns
		S0 high and S1 low (count down)	12			
		S0 and S1 high (count up)	12			
+.	Haldford office OLIVA	S0 high after S1 <sup>↑</sup> or S1 high after S0 <sup>↑</sup>	3			ns
<sup>t</sup> h	Hold time after CLK↑  Data inputs A-H		0			113
TA	Operating free-air temperature		0		70	°C

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CON	DITIONS	SN	74ALS86	7A	UNIT
PARAMETER	TEST CON	DITIONS	MIN	TYP‡	MAX	UNIT
VIK	$V_{CC} = 4.5 V,$	$I_{I} = -18 \text{ mA}$			-1.2	V
VOH	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V <sub>CC</sub> -2	2		V
V <sub>OL</sub>	Vac = 4.5.V	$I_{OL} = 4 \text{ mA}$		0.25	0.4	V
VOL	V <sub>CC</sub> = 4.5 V	$I_{OL} = 8 \text{ mA}$		0.35	0.5	V
ΙĮ	$V_{CC} = 5.5 V,$	$V_I = 7 V$			0.1	mA
lін	$V_{CC} = 5.5 V,$	$V_{I} = 2.7 V$			20	μΑ
I <sub>IL</sub>	$V_{CC} = 5.5 V,$	$V_{I} = 0.4 V$			-0.2	mA
IO§	$V_{CC} = 5.5 V,$	V <sub>O</sub> = 2.25 V	-30		-112	mA
Icc	$V_{CC} = 5.5 V$			28	45	mA

<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .



<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>§</sup> The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

# switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$C_L = 50 \text{ pf}$ $R_L = 500 \Omega$ $T_A = MIN \Omega$	2,	UNIT
			MIN	MAX	
f <sub>max</sub>			35		MHz
<sup>t</sup> PLH	CLK	RCO	4	14	ns
<sup>t</sup> PHL	GER	RCO	4	14	115
<sup>t</sup> PLH	CLK	Any Q	3	16	ns
<sup>t</sup> PHL	GER	Ally Q	3	16	115
<sup>t</sup> PLH	ENT	RCO	3	14	ns
t <sub>PHL</sub>	ENI	RCO	2	9	115
<sup>t</sup> PHL	S0 or S1 (clear mode)	Any Q	8	26	ns
<sup>t</sup> PLH	S0 or S1	RCO	4	16	no
<sup>t</sup> PHL	(count up/down)		4	16	ns
<sup>t</sup> PLH	S0 or S1 (clear mode)	RCO	4	16	ns

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

SDAS115C - DECEMBER 1982 - REVISED JANUARY 1995

# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

#### recommended operating conditions

			SN	74ALS8	69	UNIT
			MIN	NOM	MAX	UNII
Vcc	Supply voltage		4.5	5	5.5	V
V <sub>IH</sub>	High-level input voltage		2			V
V <sub>IL</sub>	Low-level input voltage				0.8	V
loн	High-level output current				-0.4	mA
loL	Low-level output current				8	mA
fclock	Clock frequency		0		35	MHz
tw(clock)	Pulse duration, CLK high or low		14			ns
		Data inputs A-H	10			
		ENP or ENT	15			
١.	Outure there is a face OUKA	S0 and S1 low (clear)	13			
t <sub>su</sub>	Setup time before CLK↑	S0 low and S1 high (load)	13			ns
		S0 high and S1 low (count down)	13			
		S0 and S1 high (count up)	13			
+,		S0 high after S1↑ or S1 high after S0↑	3			ns
th	Hold time after CLK↑  Data inputs A−H		0			115
TA	Operating free-air temperature		0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST COM	IDITIONS	SN74ALS8	369	UNIT
PARAMETER	TEST CON	IDITIONS	MIN TYP‡	MAX	UNII
VIK	$V_{CC} = 4.5 V,$	I <sub>I</sub> = -18 mA		-1.2	V
VOH	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V <sub>CC</sub> -2		V
Va	V00 - 45 V	$I_{OL} = 4 \text{ mA}$	0.25	0.4	V
VoL	V <sub>CC</sub> = 4.5 V	$I_{OL} = 8 \text{ mA}$	0.35	0.5	\ \ \
lį	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 7 V		0.1	mA
lіН	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 2.7 V		20	μΑ
I <sub>I</sub> L	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 0.4 V		-0.2	mA
ΙΟ <sup>§</sup>	$V_{CC} = 5.5 V,$	V <sub>O</sub> = 2.25 V	-30	-112	mA
lcc	V <sub>CC</sub> = 5.5 V		28	45	mA

<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .



<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>§</sup> The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

# switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ C}_{L} = 50 \text{ pF},$ $R_{L} = 500 \Omega,$ $T_{A} = \text{MIN to MAX}^{\dagger}$ $SN74ALS869$ $MIN MAX$		UNIT	
f <sub>max</sub>			35		MHz	
<sup>t</sup> PLH	CLK	RCO	4	14		
t <sub>PHL</sub>	CLK	RCO	4	14	ns	
t <sub>PLH</sub>	CLK	Any Q	3	16	ns	
<sup>t</sup> PHL	CLN	Ally Q	3	16	115	
<sup>t</sup> PLH	ENT	RCO	3	14	ns	
<sup>†</sup> PHL	ENI	RCO	2	9	115	
<sup>t</sup> PLH	tPLH S1 RCO		4	15	ns	
<sup>†</sup> PHL	(count up/down)	RCO	4	15	115	
t <sub>PLH</sub>	S0	RCO	4	16	ns	
<sup>t</sup> PHL	(clear/load)	, ROO	4	12	119	

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

SDAS115C - DECEMBER 1982 - REVISED JANUARY 1995

# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>CC</sub>	7 V
Input voltage, V <sub>I</sub>	7 V
Operating free-air temperature range, T <sub>A</sub> : SN54AS867	55°C to 125°C
SN74AS867	0°C to 70°C
Storage temperature range	65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions

			SI	N54AS86	7	SN	174AS86	7	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vcc	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage		2			2			V
V <sub>IL</sub>	Low-level input voltage				0.8			0.8	V
loh	High-level output current				-2			-2	mA
loL	Low-level output current				20			20	mA
fclock*	Clock frequency		0		40	0		50	MHz
tw(clock)*	Pulse duration, CLK high or lo	w	12.5			10			ns
tw(clear)*	Pulse duration of clear pulse,	S0 and S1 low	12.5			10			ns
		Data inputs A-H	5			4			
		ENP or ENT	9			8			
. *	Outure the a before OLIKA	S0 low and S1 high (load)	11			10			no
t <sub>su</sub> *	Setup time before CLK↑	S0 and S1 low (clear)	11			10			ns
		S0 high and S1 low (count down)	42			40			
		S0 and S1 high (count up)	42			40			
t <sub>h</sub> *	Hold time after CLK↑	Data inputs A-H	0			0			ns
tskew*	Skew time between S0 and S (maximum to avoid inadverter				8			7	ns
TA	Operating free-air temperature	9	-55		125	0		70	°C

<sup>\*</sup> On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.



# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	ARAMETER	TEST C	TEST CONDITIONS		N54AS86	<b>57</b>	SN	174AS86	7	UNIT
"	AKAMETEK	TEST CONDITIONS		MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT
٧ıĸ		$V_{CC} = 4.5 V,$	I <sub>I</sub> = -18 mA			-1.2			-1.2	V
Vон		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	I <sub>OH</sub> = −2 mA	V <sub>CC</sub> -2	2		V <sub>CC</sub> -2			V
VOL	RCO	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 2 <u>0 m</u> A, V <sub>IL</sub> on ENT = 0.7 V		0.34	0.5				V
	Other outputs		I <sub>OL</sub> = 20 mA						0.5	
II		V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 7 V			0.1			0.1	mA
1	ENT	V	V <sub>I</sub> = 2.7 V			40			40	
lіН	Other inputs	$V_{CC} = 5.5 \text{ V},$	V   = 2.7 V			20			20	μΑ
1	ENT	V 55V	V- 0.4 V			-4			-4	A
¹ı∟	Other inputs	V <sub>CC</sub> = 5.5 V,	$V_{l} = 0.4 \text{ V}$		-2		-2		-2	mA
I <sub>O</sub> ‡	-	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-30		-112	-30		-112	mA
Icc		V <sub>CC</sub> = 5.5 V			134	195		134	195	mA

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

#### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C <sub>L</sub> R <sub>L</sub>	= 50 pF = 500 C	V to 5.5 ; , o MAX§	V,	UNIT
			SN54A	S867	SN74A	S867	
			MIN	MAX	MIN	MAX	
fmax*			40		50		MHz
<sup>t</sup> PLH	CLK	RCO	5	31	5	22	ns
<sup>t</sup> PHL	OLIX	RCO	6	19	6	16	115
<sup>t</sup> PLH	CLK	Any Q	3	12	3	11	ns
<sup>†</sup> PHL	OLIX	Ally Q	4	16	4	15	113
<sup>t</sup> PLH	<del>ENT</del>	RCO	3	19	3	10	ns
<sup>t</sup> PHL	ENI	RCO	5	21	5	17	115
t <sub>PLH</sub>	ENP	RCO	5	16	5	14	ns
<sup>t</sup> PHL	ENP	RCO	5	21	5	17	115
<sup>t</sup> PHL	Clear (S0 or S1 low)	Any Q	7	23	7	21	ns

<sup>\*</sup> On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.



<sup>&</sup>lt;sup>‡</sup> The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

<sup>§</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

SDAS115C - DECEMBER 1982 - REVISED JANUARY 1995

# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>CC</sub>		 7 V
Input voltage, V <sub>I</sub>		 7 V
Operating free-air temperature range, T <sub>A</sub> :	SN54AS869	 −55°C to 125°C
	SN74AS869	 0°C to 70°C
Storage temperature range		 -65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions

			SN54AS869		SN74AS869			UNIT	
			MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vcc	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
$V_{IH}$	High-level input voltage		2			2			V
V <sub>IL</sub>	Low-level input voltage				0.7			0.8	V
loн	High-level output current			-2			-2	mA	
loL	Low-level output current			20			20	mA	
fclock*	Clock frequency				40			45	MHz
tw(clock)*	Pulse duration, CLK high or I	12.5			11			ns	
	Setup time before CLK↑	Data inputs A-H	6			5			
		ENP or ENT	10			9			
<b>.</b> *		S0 low and S1 high (load)				11			
t <sub>su</sub> *		S0 and S1 low (clear)	13			11			ns
		S0 high and S1 low (count down)	52			50			
		S0 and S1 high (count up)	52			50			
t <sub>h</sub> *	Hold time after CLK↑	Data inputs A-H	0			0			ns
TA	Operating free-air temperature				125	0		70	°C

<sup>\*</sup> On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.



# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SI	SN54AS869			SN74AS869			
P P	ARAWEIER	TEST CONDITIONS			TYP <sup>†</sup>	MAX	MIN	TYP	MAX	UNIT	
VIK		V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.2			-1.2	V	
V		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$				V <sub>CC</sub> -2	2		V	
VOH		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V <sub>CC</sub> -2*					] '		
V <sub>OL</sub>	RCO	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 20 mA, V <sub>IL</sub> on ENT = 0.7 V		0.34	0.34 0.5				V	
0-	Other outputs		I <sub>OL</sub> = 20 mA					0.34			
I <sub>I</sub>		$V_{CC} = 5.5 V,$	V <sub>I</sub> = 7 V			0.1			0.1	mA	
1	ENT	V 55V	V <sub>I</sub> = 2.7 V			40			40		
lіН	Other inputs	V <sub>CC</sub> = 5.5 V,	V   = 2.7 V	2		20	2		20	μΑ	
1	ENT	V00 - 5 5 V	V <sub>I</sub> = 0.4 V			-4			-4		
I L	Other inputs	V <sub>CC</sub> = 5.5 V,	V   = 0.4 V			-2			-2	mA	
IO <sup>‡</sup>		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-30		-112	-30		-112	mA	
Icc	_	V <sub>CC</sub> = 5.5 V			134	195		134	195	mA	

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

#### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$ = 4.5 V to 5.5 V, $C_L$ = 50 pF, $R_L$ = 500 $\Omega$ , $T_A$ = MIN to MAX§				UNIT
			SN54A	S869	SN74AS869		
			MIN	MAX	MIN	MAX	
f <sub>max</sub> *			40		45		MHz
<sup>t</sup> PLH	CLK	RCO	6	35	6	35	ns
<sup>t</sup> PHL		RCO	6	20	6	18	
<sup>t</sup> PLH	CLK	Any Q	3	12	3	11	ns
t <sub>PHL</sub>	OLK	Ally Q	4	16	4	15	110
<sup>t</sup> PLH	FNIT		3	25	3	15	ns
<sup>t</sup> PHL	ENT	RCO	6	21	6	17	115
t <sub>PLH</sub>	ENP	RCO	5	27	5	19	nc
<sup>t</sup> PHL	EINP	RCO	6	21	6	18	ns

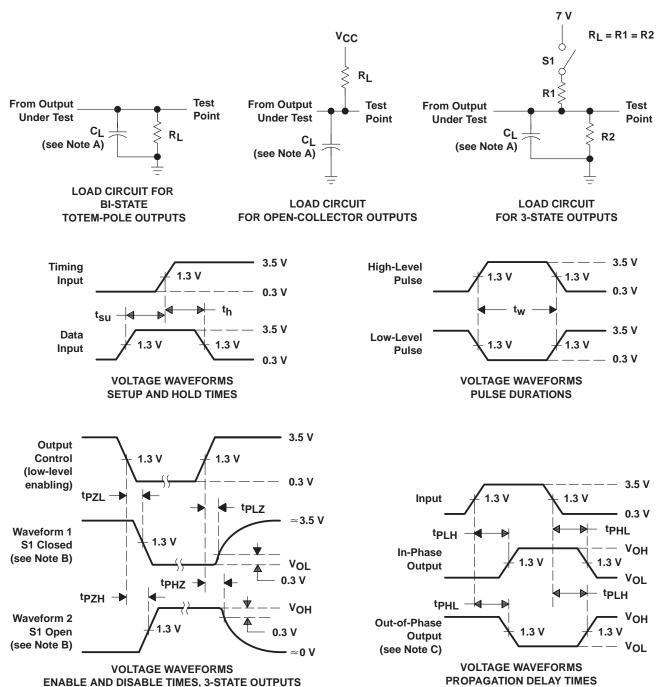
<sup>\*</sup> On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.



<sup>‡</sup> The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

<sup>§</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

#### PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR  $\leq$  1 MHz,  $t_r = t_f = 2$  ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms





www.ti.com 11-Nov-2009

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp (3)
5962-89526013A	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8952601KA	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type
5962-8952601LA	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type
5962-89668013A	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8966801KA	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type
5962-8966801LA	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type
SN54AS867JT	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type
SN54AS869JT	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type
SN74ALS867ADW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS867ADWE4	4 ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS867ADWG4	4 ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS867ANT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS867ANTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS869DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS869DWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS869DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS869NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS869NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS867DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS867DWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS867DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS867NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS867NT3	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI
SN74AS867NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS869DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS869DWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS869DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS869NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS869NT3	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI



#### PACKAGE OPTION ADDENDUM

www.ti.com 11-Nov-2009

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74AS869NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ54AS867FK	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54AS867JT	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type
SNJ54AS867W	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type
SNJ54AS869FK	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54AS869JT	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type
SNJ54AS869W	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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#### FK (S-CQCC-N\*\*)

#### **28 TERMINAL SHOWN**

#### **LEADLESS CERAMIC CHIP CARRIER**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



# NT (R-PDIP-T\*\*)

#### PLASTIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

The 28 pin end lead shoulder width is a vendor option, either half or full width.



#### W (R-GDFP-F24)

#### **CERAMIC DUAL FLATPACK**



- NOTES: A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Falls within MIL-STD-1835 GDFP2-F24 and JEDEC MO-070AD
  - E. Index point is provided on cap for terminal identification only.



# DW (R-PDSO-G24)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



#### JT (R-GDIP-T\*\*)

#### 24 LEADS SHOWN

#### **CERAMIC DUAL-IN-LINE**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

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